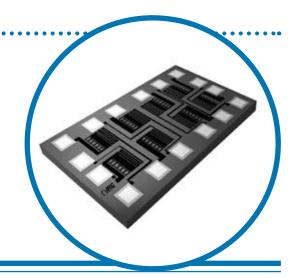
Wire Bondable Resistor Network Arrays



Chip Network Array Series

- Absolute tolerances to ±0.1%
- Tight TCR tracking to ±5ppm/°C
- Ratio match tolerances to ±0.05%
- Ultra-stable tantalum nitride resistors



IRC's TaNSil® network array resistors are ideally suited for applications that demand a small footprint. The small wire bondable chip package provides higher component density, lower resistor cost and high reliability.

The tantalum nitride film system on silicon provides precision tolerance, exceptional TCR tracking and low cost. Excellent performance in harsh, humid environments is a trademark of IRC's self-passivating TaNSil® resistor film.

For applications requiring high performance resistor networks in a low cost, wire bondable package, specify IRC network array die.

Electrical Data

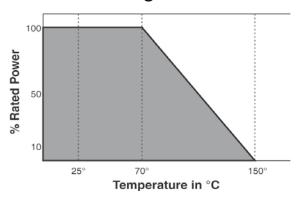
		Isolated	Bussed		
Resistance Ra	Resistance Range		10 Ω to 1.25M Ω		
Absolute Toler	ance	to ±0	0.1%		
Ratio Tolerano	10 20100 / 10 2011		to ±0.1%		
Absolute TCR	bsolute TCR to ±25ppm/°C				
Tracking TCR		to ±5ppm/°C			
Element Powe	r Rating	100mW @ 70°C	50mW @ 70°C		
Package Power Rating		8-Pad 400mW @ 70°C 16-Pad 800mW @ 70°C 24-Pad 1.0W @ 70°C			
Rated Operating Voltage (not to exceed $\sqrt{P} \times R$)		100V			
Operating Temperature		-55°C to +150°C			
Noise	Noise		<-30dB		
Substrate Mat	erial	Oxidized Silicon (10	OKÅ SiO ₂ minimum)		
Substrate Thickness		0.016″ ±0.001 (0.406mm ±0.01)			
Bond Pad	Aluminum	10KÅ minimum			
Metallization	Gold	15KÅ minimum			
Backside		Silicon (gold available)			
Passivation		Silicon Dioxide or Silicon Nitride			

TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*
±300ppm/°C	00	04
±100ppm/°C	01	05
±50ppm/°C	02	06
±25ppm/°C	03	07

*Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

Power Derating Data



TT electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT electronics' own data and is considered accurate at time of going to print.







www.bitechnologies.com www.irctt.com www.welwyn-tt.com



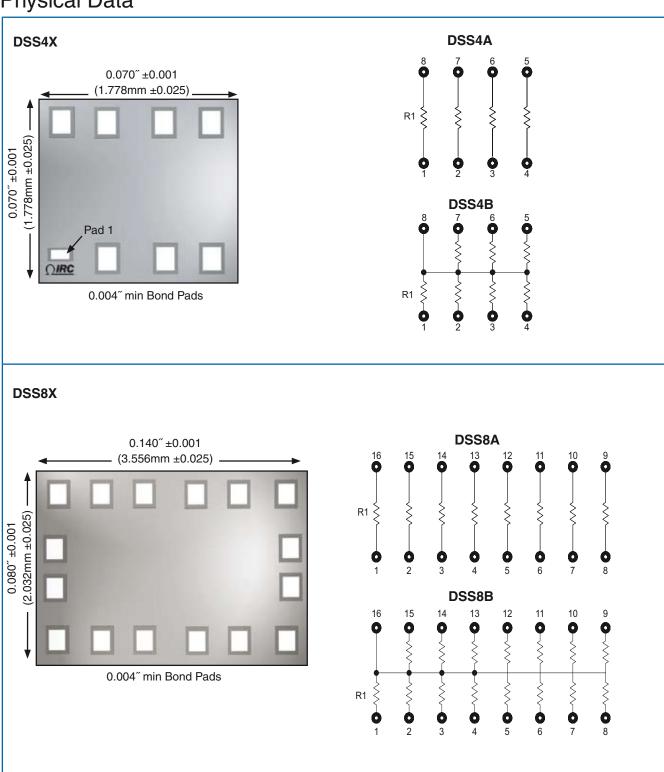
Manufacturing Capabilities Data

	Isolated schematic A				Bussed schematic B			
Absolute TCR (±ppm/°C)	Ohmic range (Ω)	Available tolerances	Available ratio tolerances	Best TCR tracking (±ppm/°C)	Ohmic range (Ω)	Available tolerances	Available ratio tolerances	Best TCR tracking (±ppm/°C)
	10 - 25	FGJ	FG	50	10 - 25	FGJ	FG	200
	26 - 50	DFGJ	CDF	10	26 - 50	FGJ	DFG	100
300	51 - 200	CDFGJ	CDFG	5	51 - 100	DFGJ	CDFG	50
300	201 - 2.5M	BCDFGJ	ABCDFG	5	101 - 200	DFGJ	BCDFG	25
					201 - 500	BCDFGJ	BCDFG	20
					501 - 1.25M	BCDFGJ	ABCDFG	5
	26 - 50	DFGJ	CDFG	10	26 - 50	FGJ	DFG	100
	51 - 200	CDFGJ	CDFG	5	51 - 100	DFGJ	CDFG	50
100	201 - 2.5M	BCDFGJ	ABFG	5	101 - 200	DFGJ	BCDFG	25
					201 - 500	BCDFGJ	BCDFG	20
				501 - 350K	BCDFGJ	ABCDFG	5	
	26 - 50	DFGJ	CDFG	10	51 - 100	DFGJ	CDFG	50
50	51 - 200	CDFGJ	CDFG	5	101 - 200	DFGJ	BCDFG	25
30	201 - 2.5M	BCDFGJ	ABFG	5	201 - 500	BCDFGJ	BCDFG	20
					501 - 1.25M	BCDFGJ	ABCDFG	5
25	51 - 200	CDFGJ	CDFG	5	201 - 500	BCDFGJ	BCDFG	20
	201 - 2.5M	BCDFGJ	ABFG	5	501 - 1.25M	BCDFGJ	ABCDFG	5





Physical Data



General Note

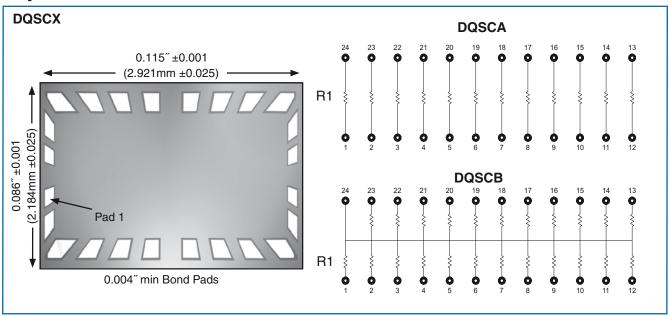




Chip Network Array Series



Physical Data



Environmental Data

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Storage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

Ordering Data

Prefix · · · · · · · ·	• WBD	DSS8	- B -	01 -	1002	- F -	В
Style · · · · · · · · · · · · · · · DSS4 = 8-pad Network DSS8 = 6-pad Network DQSC = 24-pad Network		•					•
Schematic and Terr A = Isolated; B = Bussed	mination	• • • • •	•••				
TCR/Inspection Coo Reference TCR/Inspecti		ble	• • • •	:			•
Resistance Code • 4-Digit Resistance Code Ex: 1002 = 10ΚΩ, 50R1 = 5		••••	• • • •	••••	• • •		
Absolute Tolerance J = ±5%; G = ±2%; F = ±1% D = ±0.5%; C = ±0.25%; B =	;	• • • • •	••••	••••	••••		
Ratio Tolerance Cou G = ±2%; F = ±1%; D = ±0.5 C = ±0.25%; B = ±0.1%; A =	5%;	nal) • • •	• • • •	••••	••••	• • • •	.:
Packaging Standard packaging is 2 or to discuss your specif						tions	

Team using the contact details below.



